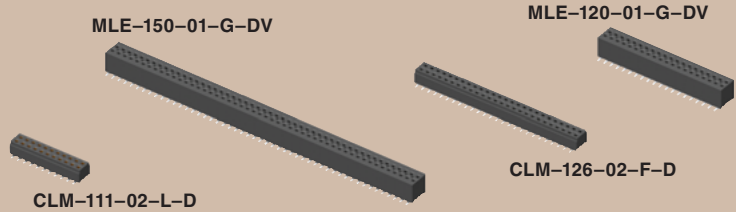




(1,00 mm) .0394"



CLM, MLE SERIES

RUGGED RELIABLE MICRO SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLM or www.samtec.com?MLE

Insulator Material:

Black LCP

Contact Material:

CLM: Phosphor Bronze

MLE: BeCu

Plating:

CLM: Au, Sn or SnPb

over 50µ" (1,27 µm) Ni

MLE: Au over 10µ" (0,25 µm) Ni

Current Rating (CLM/FTM):

2.8 A per pin

(1 pin powered per row)

Current Rating (MLE/FTM):

2.9 A per pin

(1 pin powered per row)

Operating Temp Range:

-55°C to +125°C

Contact Resistance:

MLE: 15 mΩ

Max Cycles:

MLE: 100 with 10µ" (0,25 µm) Au

Voltage Rating:

MLE: 310 VAC

Insertion Depth:

CLM: Top Entry = (1,40 mm)

.055" min., Bottom Entry =

(2,41 mm) .095" min.

(Add board thickness for

correct post OAL)

MLE: (1,63 mm) .064" to

(3,18 mm) .125" with

(0,38 mm) .015" wipe,

pass-through, or

(2,44 mm) .096" minimum

for bottom entry

Insertion Force:

CLM: 1.5 oz (0,42 N) average

MLE: 2.70 oz (0,75 N) average

Withdrawal Force:

CLM: .75 oz (0,21 N) average

MLE: 0.50 oz (0,14 N) average

RoHS Compliant: Yes

Lead-Free Solderable: Yes

SMT Lead Coplanarity:

(0,10 mm) .004" max (02-25)

(0,15 mm) .006" max (26-50)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Note: Some lengths, styles and options are non-standard, non-returnable.

CLM - **1** NO. PINS PER ROW - **02** PLATING OPTION - **D** OPTIONS

Mates with: FTM, FTMH, MW

02 thru 50

-F
= Gold flash on contact, Matte Tin on tail

-L
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

-BE
= Bottom Entry (Required for bottom entry)

-K
= (3,50 mm) .138" DIA Polyimide film Pick & Place Pad (7 positions minimum)

-P
= Pick & Place Pad (7 positions minimum)

-PA
= Pick & Place Pad with integral Alignment Pin

-TR
= Tape & Reel Packaging

No. of positions x (1,00) .03937 + (0,318) .0125

(1,00) .03937

(2,54) .100

(5,72) .225

(3,57) .140

(2,41) .095

(1,00) .03937

(0,28) .011

(3,81) .150

(2,26) .089

(1,36) .054

(8,26) .325 by A

(3,00) .118

(0,89) .035 DIA

(7,00) .275

-PA

APPLICATION

Pass-Thru

PIN/ROW	A
04-15	(3,56) .140
16-50	(7,11) .280

ALSO AVAILABLE (MOQ Required)

- Alignment pin
- Other Gold plating options

Contact Samtec.

MLE - **1** NO. PINS PER ROW - **01** PLATING OPTION - **DV** OPTIONS

Mates with: FTM, FTMH, MW

02 thru 50

-G
= 10µ" (0,25 µm) Gold

-A
= Alignment Pin (3 positions minimum) Metal or plastic at Samtec discretion.

-K
= (4,00 mm) .1575" DIA Polyimide film Pick & Place Pad (5 positions minimum)

-P
= Metal Pick & Place Pad (5 positions minimum)

-TR
= Tape & Reel Packaging

No. of positions x (1,00) .03937 + (0,20) .008

(1,00) .03937

(1,00) .03937

(0,30) .012

(3,07) .121

(0,71) .028

(0,64) .025 DIA

-A

(6,35) .250 x (3,18) .125

(4,32) .170

(3,30) .130

(3,50) .138

-P

Due to technical progress, all designs, specifications and components are subject to change without notice.

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